



US 20240213041A1

(19) **United States**

(12) **Patent Application Publication**
KIM et al.

(10) **Pub. No.: US 2024/0213041 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **SUBSTRATE PROCESSING DEVICE**

Publication Classification

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(51) **Int. Cl.**

H01L 21/67 (2006.01)

C23C 16/48 (2006.01)

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(52) **U.S. Cl.**

CPC **H01L 21/67017** (2013.01); **C23C 16/483**
(2013.01)

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(21) Appl. No.: **18/543,499**

(22) Filed: **Dec. 18, 2023**

(30) **Foreign Application Priority Data**

Dec. 22, 2022 (KR) 10-2022-0182172

(57)

ABSTRACT

A substrate processing device includes a substrate support portion supporting a substrate, a fluid supply portion arranged above the substrate support portion and configured to supply an initiator and a monomer toward the substrate, and a laser generation portion configured to irradiate a laser in a direction intersecting a direction in which the initiator and the monomer are supplied and parallel to a surface of the substrate, wherein the initiator and the monomer are polymerized by the laser and deposited on the substrate.

